

intel® Technical Advisory

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15220 NW Greenbrier Parkway
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Support for Intel® cD0 Stepping of Pentium® III and Celeron® Speeds 800/850 MHz

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Products Affected

ISP1100

Description

Intel has completed the validation of a thermal heat sink solution with the ISP1100 for the use of cD0 step Intel Pentium® III processors and Intel Celeron™ processors. The heat sink solution must be used when running the ISP1100 with processor clock speeds of 800MHz and 850MHz for both the Celeron® and Pentium III® processors. Running the system with these processors without this heat sink will void warranty support.

Root Cause

This heat sink provides the required processor thermal cooling when using cD0 step Celeron™ and Pentium® III processors at 800MHz and 850MHz processor speeds.

Corrective Action / Resolution

The Foxconn Electronics, Inc., part number PK0881AEDAUGB, heat sink is required to meet the thermal cooling requirements for the following S-spec processors:

Pentium III®	Celeron™
SL49G	SL5EB
SL4Z2	SL54P
SL4KF	SL5WW
SL4ZN	SL5EC
	SL54Q
	SLWX

The air baffle included with each ISP1100 1U Server Platform is NOT required when using the Foxconn Electronics PK0881AEDAUGB heat sink.

Please contact your Intel Sales Representative if you require more specific information about this issue.

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